

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	90	(ring near10 die near10 (spreader or sink or heatsink))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 17:31
L8	18	(ring near10 die near10 (spreader or sink or heatsink)) and (flipchip or flip or flip-chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 17:32
L9	16	(ring near10 die near10 (spreader or sink or heatsink)) and (flipchip or flip or flip-chip) and (epoxy or resin or encapsulant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 17:32
L10	2	(ring near10 die near10 (spreader or sink or heatsink)).clm. and (flipchip or flip or flip-chip) and (epoxy or resin or encapsulant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 17:32

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L12	1	I11 and ((thermal or thermally) near (conductive or conducting) near adhesive).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 17:51
L13	0	I11 and ((thermal or thermally) near (conductive or conducting) near adhesive) near5 (thick or thickness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 17:51
L14	40	((thermal or thermally) near (conductive or conducting) near adhesive) near5 (thick or thickness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 17:52
L15	3	((thermal or thermally) near (conductive or conducting) near adhesive) near5 (thick or thickness) near5 mil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 17:52